

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

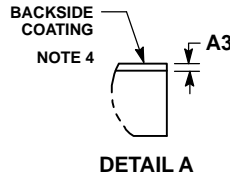
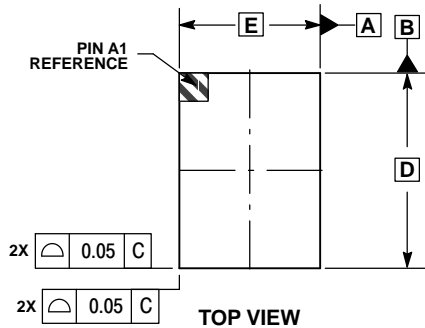
ON Semiconductor®



SCALE 4:1

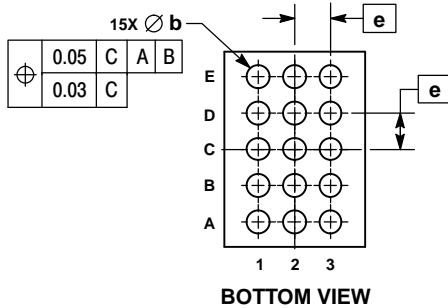
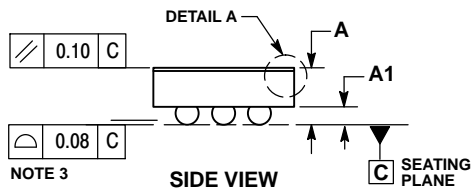
WLCSP15, 2.15x1.55
CASE 567HY
ISSUE B

DATE 30 APR 2015

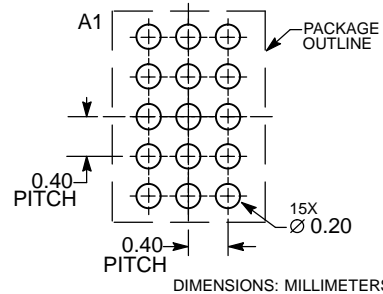


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
 4. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.65
A1	0.16	0.26
A3	0.025 REF	
b	0.21	0.31
D	2.15 BSC	
E	1.55 BSC	
e	0.40 BSC	



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP15, 2.15X1.55	PAGE 1 OF 2

